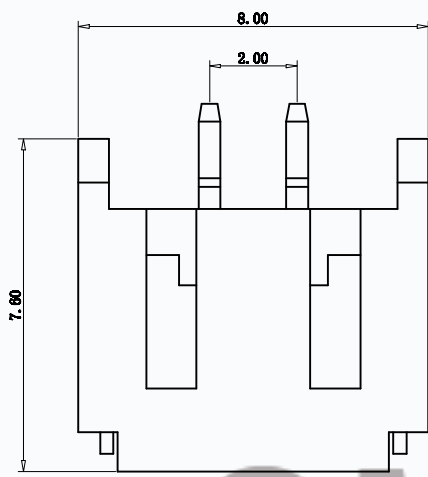
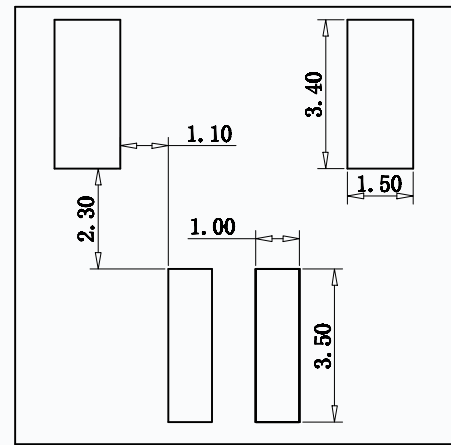
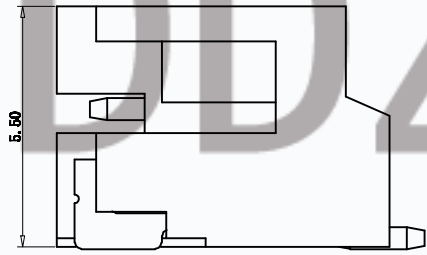
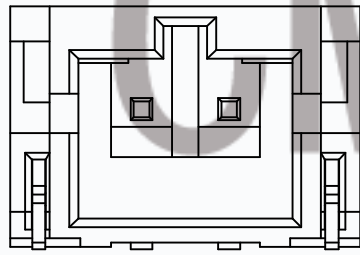


REV.	DESCRIPTION	APPD	DATE



NOTES:

- 1. MATERIAL:
 HOUSING: HIGH TEMPERATURE THERMOPLASTIC
 UL94V_0
 CONTACT: COPPER ALLOYS.
 COVER: COPPER ALLOYS OR STEEL.
- 2. PLATING:
 UNDERPLATE: NICKEL.
 CONTACT AREA: GOLD OVER NICKEL.
 SOLDER AREA: TIN OVER NICKEL.
- 3. MULTIMEDIA CARD COMPATIBLE



PART NO:		MATERIAL:		CMTDDZ 东莞市田都科技有限公司 Dongguan TianDu Technology Co., Ltd.	
LOT NO:		FINISH:			
UNIT: MM	SIZE: A4	COLOR:		TITLE: 2.0间距 卧贴	
TOLERANCES:		GENERAL ANGLE:		DR: ERIC	DWG NO: T19-20FW 系列
X.X=±0.35	X.XX=±0.25	X.X=±3.0°	X.XX=±2.0°	CHE:	
APP:		SCALE: 1:1	SHEET: 1 OF 1		